DNA 1170 Series

Desktop Cyber Security Appliance w/ Intel Atom® C5000 Processor, 8 x 1GbE Copper and 4 x 10GbE Fiber Ports

4G LTE Module   5G Module   6 Wi-Fi   BYPASS

Main Features

- Intel Atom® C5315/C5325 processor
- 2 x DDR4 SODIMM, up to 16GB
- 8 x 1GbE RJ45 ports
- 4 x SFP+ ports

- 1 x 65W 19V AC power adapter
- Supports Wi-Fi 6E (optional)
- Supports LTE/5G (optional)
- 4 x 1GbE RJ45 ports with 2 x bypass pairs (optional)

Product Overview

DNA 1170 Series is NEXCOM cyber security appliance offering server-grade performance in a desktop form factor. Powered by Intel Atom® C5000 series processor with up to 8 cores and embedded Intel® QAT feature, it features eight 1GbE copper and four 10GbE fiber ports to meet various requirements for fixed wired connectivity. To meet the increasing demand for wireless connectivity, a dedicated SKU reserves 5G/LTE and/or Wi-Fi 6E modules installation, expanding the maximal quantity of connected devices and adding wireless routes. Optional features such as storage expansion with a 2.5" SSD and enabling bypass function on four 1GbE RJ45 ports broaden the available use cases and application scenarios.

Specifications

Main Board
- Intel Atom® C5000 processor w/ QAT
  - Intel Atom® processor C5315, BGA type, 4 cores/2.4 GHz for DNA 1170
  - Intel Atom® processor C5325, BGA type, 8 cores/2.4 GHz for DNA 1170A
  - Intel Atom® processor C5325, BGA type, 8 cores/2.4 GHz for DNA 1170W

Main Memory
- 2 x DDR4 2933 SODIMM, up to 16GB

Storage
- 1 x M.2 2242 for SATA 3.0
- 2 x 2.5" SSD SATA 3.0 (DNA 1170W)

Interface External
- Button: power and reset
- LED: status/MGMT/HA/PWR1/PWR2/SSD/LAN
- LED (optional): bypass/5G LTE/Wi-Fi
- 1 x RJ45 console port

- 3 x USB 3.0 connector
- 1 x Nano SIM slot (DNA 1170W)
- 1 x 1G RJ45 management port
- 8 x 1GbE RJ45 ports
  - 4 x 1GbE RJ45 ports with 2 x bypass pairs (optional)
- 4 x SFP+ ports
- 1 x Fixed smart fan
- 2 x Power inlets
- 6 x Antenna holes (4 x antennas for 5G LTE, 2 x antennas for Wi-Fi 6E) (DNA 1170W)

Interface Internal
- 1 x mini-PCIe slot for Wi-Fi module (DNA 1170W)
- 1 x M.2 3042 Key B for 5G/LTE module (DNA 1170W)
- 1 x TPM header

Power
- 1 x 65W 19V AC power adapter
  - Second 65W 19V AC power adapter for power redundancy (optional)

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Dimension and Weight
- Chassis dimension (mm): 340 x 250 x 44 (W x D x H)
- Package dimension(mm): 436 x 346 x 198 (W x D x H)
- Without packing: 2.9kg
- With packing: 4.3kg

Environment
- Operating temperature: 0°C~40°C
- Storage temperature: -20°C~80°C
- Relative humidity: 10%~90% non-condensing

Certification
- CE/FCC class B

Ordering Information

- **DNA 1170 (P/N: TBD)**
  Intel Atom® processor C5315, BGA type 4 cores/2.4 GHz, w/ 4 x SFP+ & 8 x 1GbE RJ45 ports

- **DNA 1170A (P/N: 10L00117001X0)**
  Intel Atom® processor C5325, BGA type 8 cores/2.4 GHz, w/ 4 x SFP+ & 8 x 1GbE RJ45 ports

- **DNA 1170W (P/N: TBD)**
  Intel Atom® processor C5325, BGA type 8 cores/2.4 GHz, w/ 4 x SFP+ & 8 x 1GbE RJ45 ports, 1 x mini-PCIe slot for Wi-Fi module & 1 x M.2 3042 Key B for 5G/LTE module